

Application

This material is used to introduce lead into very low melting point sealing glasses such as solder glass for assembly of television tubes, display tubes and integrated circuit packages. It is available in either granulated or ground forms. It is produced from lead having a very low level of radio activity to protect integrated circuits from damage by alpha particles.

Physical Properties

Color.....White to pale yellow
 Form.....Granulated or ground
 Density.....6.98 - 7.07 g/cc
 Melting Point.....490 - 510°C. (914 - 950°)

Chemical Composition

Elements	Range
PbO (litharge)	87.5% +/- 0.3%
B ₂ O ₃ (boric oxide)	12.5% +/- 0.3%
H ₂ O (water)	less than 0.03%

Trace Elements

Trace Elements	Maximum (%)
Fe ₂ O ₃	0.0100
ZnO	0.0008
Cu ₂ O	0.0006
Ag	0.0015
Bi ₂ O ₃	0.0100
As ₂ O ₅ , Sb ₂ O ₃ , SnO ₂	0.0009
Ni, Te, Th, Cd	0.0006
Co, Cr, Mn, Se	0.0002

Typical Screen Analysis (U.S. Standard Sieve)	Granular (%)	Ground (%)
Greater than 7 mesh	0	0
Greater than 80 mesh	95	0
Less than 80 mesh	5	0
Alpha Particle Emission < 0.8 c/cm ² /hr		

Packaging
50 lb. / 22.68 kg Paper bags
28-gallon steel drums (700 lbs. / 317.51 kg)
Special packaging may be available upon request

Note:

This data sheet illustrates typical values for this product. If specific characteristics are required that are different from these values, please contact your area sales representative.



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